CLAIMS

1. A copper foil with a blackened surface or layer wherein one or both surfaces of a copper foil is subject to black treatment, and having a color difference $\Delta L^* \leqq -70$ and chroma $C^* \leqq 15$ of a black-treated surface when measured by a color difference meter represented by black; $\Delta L^* = -100$, white; $\Delta L^* = 0$.

2. The copper foil with a blackened surface or layer according to claim 1, wherein one or both surfaces of a copper foil is subject to black treatment, and the surface subject to black treatment has a glossiness $\leqq 15$.

3. The copper foil with a blackened surface or layer according to claim 1 or claim 2, wherein the coarsened grains of a processed surface in which one or both surfaces of a copper foil is subject to black treatment is 1μm or less, surface roughness Ra of said surface is 0.5μm or less, Rt is 4.0μm or less, and Rz is 3.5μm or less.

4. The copper foil with a blackened surface or layer according to any one of claims 1 to 3 having a black processed surface coated with at least one or more types selected from Co, Ni-Cu, Co-Cu and Ni-Co-Cu by electro plating.

5. The copper foil with a blackened surface or layer according to claim 4, wherein the Ni mass of deposit per unit area in the Ni-Cu plating process is 200 to 1000mg/m^2, or the Ni + Co mass of deposit per unit area of a plated surface subject to the Ni or Ni-Co plating process after the Ni-Cu plating process is 250 to 1500mg/m^2.

6. The copper foil with a blackened surface or layer according

to claim 4, wherein the Ni + Co mass of deposit per unit area in the Ni-Co-Cu plating process is 130 to 1000mg/m^2, or the Ni + Co mass of deposit per unit area of a plated surface subject to the Ni or Ni-Co plating process after the Ni-Co-Cu plating process is 250 to 1500mg/m^2.

7. The copper foil with a blackened surface or layer according to claim 4, wherein the Co mass of deposit per unit area in the Co-Cu plating process is 300 to 1000mg/m^2, or the Ni + Co mass of deposit per unit area of a plated surface subject to the Ni or Ni-Co plating process after the Co-Cu plating process is 350 to 1500mg/m^2.

8. The copper foil with a blackened surface or layer according to claim 4, wherein the Co mass of deposit per unit area in the Co plating process is 1000 to 5000mg/m^2, or the Ni + Co mass of deposit per unit area of a plated surface subject to the Ni or Ni-Co plating process after the Co plating process is 1050 to 2000mg/m^2.

9. The copper foil with a blackened surface or layer according to any one of claims 1 to 8, wherein the copper foil is an electrolytic copper foil or rolled copper foil of 8 to 18μm.

10. The copper foil with a blackened surface or layer according to any one of claims 1 to 9, further comprising a rust prevention processed layer on the layer subject to black treatment.

11. The copper foil with a blackened surface or layer according to claim 10, wherein the rust prevention processed layer is one or more types selected from Cr, Zn, Zn-Ni and Zn-Ni-P.

12. The copper foil with a blackened surface or layer according to any one of claims 1 to 11, wherein said copper foil is a plasma display copper foil.